

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT5704382

SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
Name		Execution Date
DOW SILICONES CORPORATION		08/23/2019
RECEIVING PARTY DATA		
Name:	DDP SPECIALTY ELECTRONIC MATERIALS US 9, LLC	
Street Address:	974 CENTRE ROAD	
City:	WILMINGTON	
State/Country:	DELAWARE	
Postal Code:	19805	
PROPERTY NUMBERS Total: 14		
Property Type	Number	
Patent Number:	8343854	
Patent Number:	9017804	
Patent Number:	8860040	
Patent Number:	9018639	
Patent Number:	9738991	
Patent Number:	9797064	
Patent Number:	8940614	
Patent Number:	9337277	
Patent Number:	9279192	
Patent Number:	9165779	
Patent Number:	10002760	
Application Number:	15419993	
Application Number:	15421220	
Application Number:	15548082	
CORRESPONDENCE DATA		
Fax Number:	(408)341-3098	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>		
Phone:	(408)341-3059	
Email:	Monica.Moreno@wbd-us.com	

Correspondent Name: WOMBLE BOND DICKINSON (US) LLP
Address Line 1: P.O. BOX 7037
Address Line 4: ATLANTA, GEORGIA 30357-0037

ATTORNEY DOCKET NUMBER: 247166-000XXX

NAME OF SUBMITTER: JOSEPH BACH

SIGNATURE: /Joseph Bach/

DATE SIGNED: 09/05/2019

Total Attachments: 27

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**FORM OF
PATENT ASSIGNMENT**

This PATENT ASSIGNMENT (this "Assignment"), dated as of November 1, 2018 (the "Effective Date"), is by and between Dow Silicones Corporation (f/k/a Dow Corning Corporation), a Michigan corporation ("Assignor") and DDP Specialty Electronic Materials US 9, LLC, a Delaware limited liability company ("Assignee"), (each a "Party" and collectively, the "Parties").

WHEREAS, Assignor owns the issued patents and patent applications set forth on Schedule A hereto (the foregoing, including all patents issuing from any patent applications, collectively, the "Assigned Patents"); and

WHEREAS, the Parties hereto agree that the Assignor contribute, transfer, assign and convey to the Assignee all of its right, title and interest in and to the Assigned Patents and that the Assignee accept such contribution, transfer, assignment and conveyance of such Assigned Patents;

NOW, THEREFORE, in consideration of the foregoing and the covenants and agreements contained in this Assignment, the receipt and sufficiency of which are hereby acknowledged, the Parties hereby agree as follows:

1. Conveyance. Assignor hereby assigns, transfers and conveys to Assignee all of Assignor's right, title and interest in and to the Assigned Patents, together with any and all (a) related continuations, continuations-in-part, divisionals, reissues, reexaminations, substitutions, extensions, and foreign equivalents thereof and (b) priority rights derived from any the Assigned Patents, or the items described in the foregoing subsection (a), by virtue of the International Convention for the Protection of Industrial Property and any other rights provided under applicable treaties or conventions, including rights in any and all provisional applications, together with all rights and remedies against past, present, and future infringement, misappropriation, or other violation thereof, including the right to enforce the foregoing and to sue for and recover profits and damages for any and all infringements, misappropriations or violations thereof, whether past, present or future, to the full end of the term or terms for which said patents may be granted, as fully and entirely as the same would have been held and enjoyed by Assignor without this assignment (the rights transferred under this Section 1 cumulatively, the "Assigned Rights").

2. Recordation; Further Assurances. Assignor and Assignee shall each take any and all additional actions as may be reasonably necessary to effect the transactions contemplated hereby, including Assignor's execution of individual assignment documentation prepared by Assignee at Assignee's expense for filing with the authorities of each individual country. In furtherance of the foregoing, Assignor agrees that with respect to the Assigned Patents it will enter into an assignment agreement suitable for filing with the authorities of each individual country (each an "Recordal Instrument"). The Parties agree that any Recordal Instrument shall give no greater rights or remedies in respect of the transaction completed in such Recordal

Instrument than those provided for herein and Section 4 of this Assignment shall apply to any Recordal Instrument as if fully set forth therein. As between the Parties, the responsibility to file assignments with the national patent offices of each country for the Assigned Patents shall be on the Assignee and the Assignee shall bear the cost of filing such assignments (unless, as of the Effective Date, the patent registration or application is not properly recorded in the name of the Assignor or an Affiliate of Assignor, in which case, at the request of Assignee, the Parties shall reasonably cooperate to make the necessary corrective filings and recordals of the documents that are available to them and shall split evenly any expenses in connection with the foregoing corrections and each Party shall provide any receipts and expense documentation to the other Party for the purposes of splitting such expenses).

3. Prosecution and Maintenance. For the avoidance of doubt but without limiting the obligations set forth in Section 2 hereof, as of and following the Effective Date, Assignor will have no responsibility to take any action to maintain any of the patents included in the Assigned Rights or further prosecute or seek issuance of any patent applications included in the Assigned Rights, including payment of fees, responses to any office action or other inquiries from agents of governmental entities or registrars, or otherwise.

4. No Claims. Except with respect to Section 2 of this Assignment, neither Party nor any of their respective affiliates or representatives will have, or be subject to, any liability or indemnification obligation under this Assignment to the other Party, any of its affiliates or representatives or any other entity or person resulting from, or in connection with, this Assignment or the transactions contemplated hereby. Except with respect to Section 2, each of the Parties hereby agrees (a) not to bring any claim or Action (as defined herein) under this Assignment against the other Party, its affiliates or representatives and (b) to cause its respective affiliates and representatives to comply with this Section 4. "Action" shall mean any claims, actions, suits, inquiries, proceedings or investigations by or before any governmental authority or arbitral tribunal.

5. Disclaimer of Representations and Warranties. ASSIGNEE (ON BEHALF OF ITSELF AND ITS AFFILIATES) UNDERSTANDS AND AGREES THAT NO PARTY TO THIS ASSIGNMENT IS REPRESENTING OR WARRANTING IN ANY WAY IN THIS ASSIGNMENT, AND HEREBY EXPRESSLY DISCLAIMS ALL REPRESENTATIONS AND WARRANTIES, AS TO THE ASSIGNED PATENTS AND THE OTHER ASSIGNED RIGHTS, AS TO ANY CONSENTS OR APPROVALS (INCLUDING APPROVALS FROM ANY GOVERNMENTAL ENTITIES) REQUIRED IN CONNECTION HERewith OR THEREWITH, AS TO THE VALUE OR FREEDOM FROM ANY SECURITY INTERESTS OF OR THE NON-INFRINGEMENT OR ABSENCE OF OTHER VIOLATION, VALIDITY OR ENFORCEABILITY OR ANY OTHER MATTER CONCERNING THE ASSIGNED PATENTS AND OTHER PATENTS AND PATENT APPLICATIONS INCLUDED IN THE ASSIGNED RIGHTS, AND ALL OF THE ASSIGNED PATENTS AND OTHER ASSIGNED RIGHTS ARE BEING TRANSFERRED ON AN "AS IS, WHERE IS" AND "WITH ALL FAULTS" BASIS.

6. Successors and Assigns. The provisions of this Assignment and the obligations and rights hereunder shall be binding upon, inure to the benefit of and be enforceable by (and against) the Parties and their respective successors and permitted transferees and assigns.

7. Counterparts. This Assignment may be executed in more than one counterpart, all of which shall be considered one and the same agreement, and shall become effective when one or more such counterparts have been signed by each of the Parties and delivered to each of the Parties.

8. Title and Headings. Titles and headings to sections herein are inserted for the convenience of reference only and are not intended to be a part of or to affect the meaning or interpretation of this Assignment.


9. Governing Law. This Assignment and any dispute arising out of, in connection with or relating to this Assignment shall be governed by and construed in accordance with the Laws of the State of Delaware, without giving effect to the conflicts of laws principles thereof.

[Signature Page Follows]

IN WITNESS WHEREOF, Assignor and Assignee have duly executed this Assignment as of the date first written above.

ASSIGNOR:

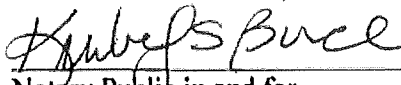
DOW SILICONES CORPORATION

By: 
Name: Jonathan P. Wendt
Title: Secretary

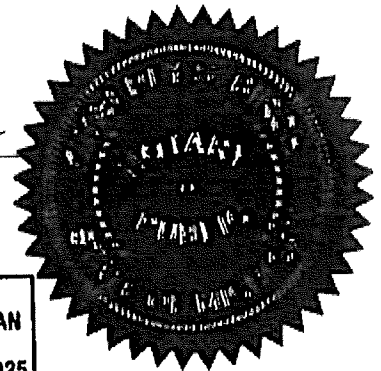
THE STATE OF MICHIGAN

County of Midland

This instrument was executed before me on this 23rd day of August, 2019, by Jonathan P. Wendt, the Secretary of Dow Silicones Corporation, a Michigan corporation, on behalf of said company.


Notary Public in and for
The State of Michigan

KIMBERLY S. BIRCH
NOTARY PUBLIC - STATE OF MICHIGAN
COUNTY OF MIDLAND
My Commission Expires March 16, 2025
Acting in the County of MIDLAND



Signature Page to Patent Assignment

PATENT
REEL: 050296 FRAME: 0370

Acknowledged and Accepted:

ASSIGNEE:

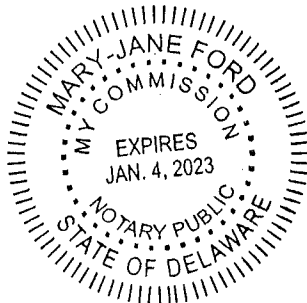
DDP SPECIALTY ELECTRONIC
MATERIALS US 9, LLC

By: Calissa W. Brown
Name: Calissa W. Brown
Title: Assistant Secretary

THE STATE OF DELAWARE

County of New Castle

This instrument was executed before me on this 27th day of August, 2019, by
Calissa W. Brown, the Assistant Secretary (title) of DDP Specialty
Electronic Materials US 9, LLC, a Delaware limited liability company, on behalf of said
company.



Mary-Jane Ford
Notary Public in and for
The State of DELAWARE

MARY-JANE FORD
Printed or Typed Name of Notary

My commission expires JAN. 4, 2023

Signature Page to Patent Assignment

SCHEDULE A TO PATENT ASSIGNMENT

SCHEDULE A
PATENTS

CASE REFERENCE COUNTRY	TITLE	OWNER	FILING DATE	APP. NUMBER	PUB. NUMBER	GRANT DATE	GRANT NUMBER
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REDACTED

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PATENT

REEL: 050296 FRAME: 0375

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REDACTED

REDACTED

REDACTED

REDACTED

DC10739-US- PCT	United States Of America	Method of Reducing Memory Effects in Semiconductor Epitaxy	DOW SILICONES CORPORATION	05/29/2009 12/993938	20110073874	01/01/2013 8343854
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REDACTED

REDACTED

SCHEDULE A
PATENTS

REDACTED

DC11526-US-DIV	United States Of America	Flat SiC Semiconductor Substrate	DOW SILICONES CORPORATION	03/11/2015	14/644980	20150194319	10/20/2015 9165779
DC11526-US-NP	United States Of America	Flat SiC Semiconductor Substrate	DOW SILICONES CORPORATION	08/06/2013	13/959896	20140117380	04/28/2015 9018639

REDACTED

DC11578-US-CNT	United States Of America	High Voltage Power Semiconductor Devices On SiC	DOW SILICONES CORPORATION	09/16/2014	14/487774	20150333125	05/10/2016 9337277
DC11578-US-NP	United States Of America	High Voltage Power Semiconductor Devices On SiC	DOW SILICONES CORPORATION	08/06/2013	13/959855	20140070234	10/14/2014 8860040

SCHEDULE A
PATENTS

REDACTED

DC11662-US- DIV	United States Of America	SIC Crystal and Wafer Cut from Crystal with Low Dislocation Density	DOW SILICONES CORPORATION	01/30/2017	15/419993	20170137963	
DC11662-US- NP	United States Of America	SIC Crystal and Wafer Cut from Crystal with Low Dislocation Density	DOW SILICONES CORPORATION	10/18/2013	14/058167	20140220296	10/24/2017 9797064

REDACTED

DC11663-US- NP	United States Of America	Method To Reduce Dislocations in SIC Crystal Growth	DOW SILICONES CORPORATION	07/08/2013	13/937149	20140220325	04/28/2015 9017804
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REDACTED

DC11664-US- DIV	United States Of America	SIC Crystal With Low Dislocation Density	DOW SILICONES CORPORATION	01/31/2017	15/421220		
DC11664-US- NP	United States Of America	SIC Crystal With Low Dislocation Density	DOW SILICONES CORPORATION	08/09/2013	13/963989	20140220298	08/22/2017 9738991

REDACTED

REDACTED

REDACTED

DC11735-US- United States Of SiC Substrate With SiC DOW SILICONES
PCT America Epitaxial Film CORPORATION 03/14/2014 14/213888 20140264384 01/27/2015 8940614

REDACTED

REDACTED

REDACTED

DC11943-US- DIV	United States Of America	METHOD FOR MANUFACTURING SIC WAFER FIT FOR INTEGRATION WITH POWER DEVICE MANUFACTURING TECHNOLOGY	DOW SILICONES CORPORATION	03/04/2016 15/061959	20160189956	06/19/2018 10002760
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DC11943-US- NP	United States Of America	METHOD FOR MANUFACTURING SIC WAFER FIT FOR INTEGRATION WITH POWER DEVICE MANUFACTURING TECHNOLOGY	DOW SILICONES CORPORATION	12/29/2014 14/585101	2016-0032486	03/08/2016 9279192
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REDACTED

REDACTED

DC11995-US- PCT	United States Of America	Furnace for Seeded Sublimation of Wide Band Gap Crystals	DOW SILICONES CORPORATION	01/29/2016 15/548082	20180002828
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